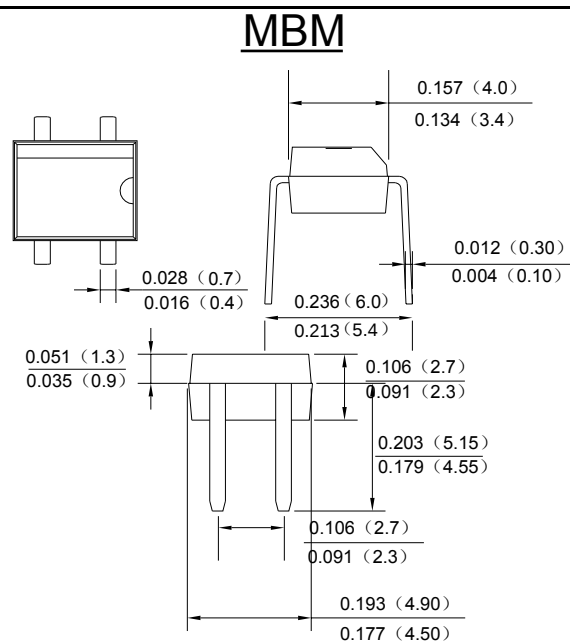


Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-25A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	EMB1MN	EMB2MN	EMB4MN	EMB6MN	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM}	100	200	400	600	V
	V_{RWM}					
	V_{DC}					
RMS Reverse Voltage	V_{RMS}	70	140	280	420	V
Average Rectified Output Current (Note 1)@ $T_A=40^{\circ}C$	I_o	0.5				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	25				A
Forward Voltage per element @ $I_F=0.5A$	V_{FM}	0.95		1.25	1.75	V
Peak Reverse Current @ $T_A=25^{\circ}C$ At Rated DC Blocking Voltage @ $T_A=125^{\circ}C$	I_R	5.0 500				μA
Maximum reverse recovery time (Note 3)	T_{RR}	35				ns
Typical Junction Capacitance per leg	C_J	13				pF
Typical Thermal Resistance per leg (Note 4)	$R_{\theta JA}$	70				$^{\circ}C/W$
	$R_{\theta JL}$	20				
Operating and Storage Temperature Range	T_J, T_{STG}	-55to+150				$^{\circ}C$

Note:1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{rr}=0.25\text{A}$.

3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

EMB1MN THRU EMB6MN

